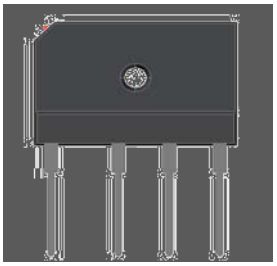
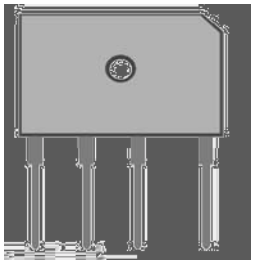
RoHS
COMPLIANT





- Glass passivated chip junction
- Thin single in-line package
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

- : PB
  Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- : Tin plated leads, solderable per J-STD-002 and JESD22-B102
- As marked on body

■ (Ta=25 Unless otherwise specified

Device marking code				YG50DD60	YG50DD80	YG50DD100	YG50DD120
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	V	600	800	1000	1200
Maximum RMS Voltage		V_{RMS}	V	420	560	700	840
Maximum DC blocking Voltage		V_{DC}	V	600	800	1000	1200
Average rectified output current @60Hz sine wave, R-load	With heatsink Tc =100	I_O	A	50*2			
	Without heatsink Ta =25			15*2			
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25		I_{FSM}	A	600			
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25				1200			
Current squared time @1ms≤t≤8.3ms Tj=25 , Rating of per diode		I^2t	A^2s	1490			
Storage temperature		T_{stg}		-55 ~ +150			
Junction temperature		T_j		-55 ~ +150			
Dielectric strength @ Terminals to case, AC 1 minute		V_{dis}	KV	2.5			
Mounting torque @Recommend torque 5kg cm		Tor	kg cm	8			

■ Ta=25 Unless otherwise specified

Maximum instantaneous forward voltage drop per diode	V_F	V	I_{FM}=25.0A	1.05			
Maximum DC reverse current at rated DC blocking voltage per diode	I_R	μA	T_j =25	5			
			T_j =125	500			
Typical junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	292			

■ T_a=25 Unless otherwise specified

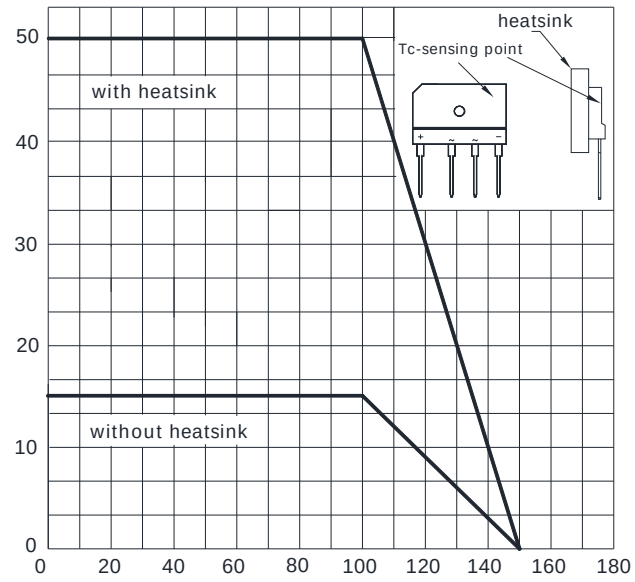
Thermal Resistance	Between junction and ambient, Without heatsink	$R_{\theta J-A}$	/W	18.0			
	Between junction and case, With heatsink	$R_{\theta J-C}$		0.75			

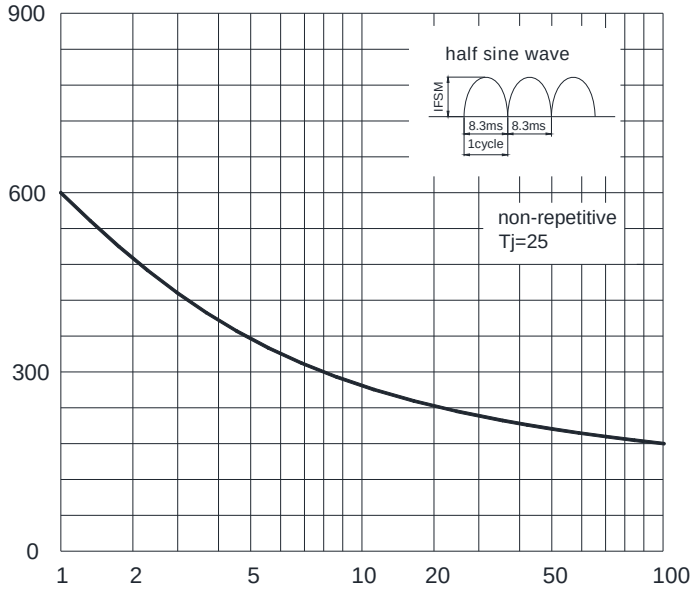
Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

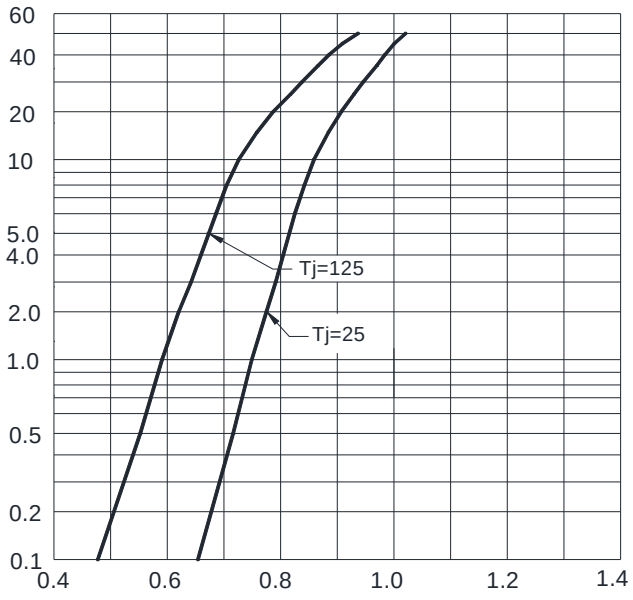
■ (Example)

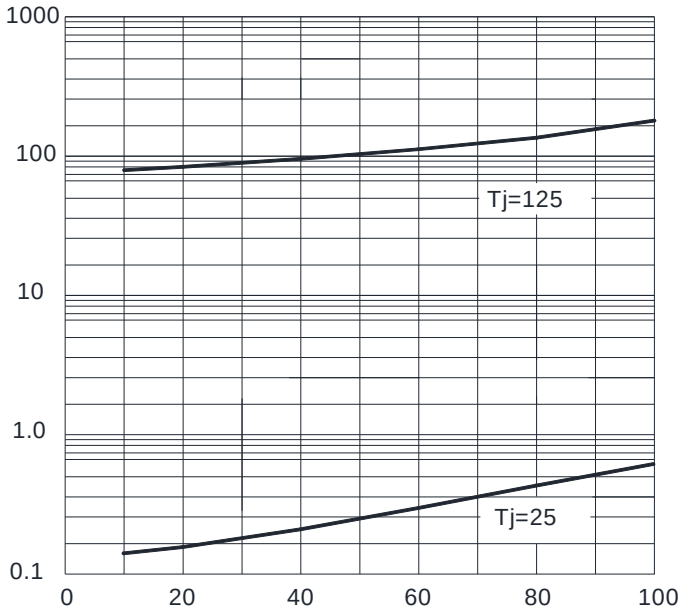
YG50DD60 THRU YG50DD120	B1	Approximate 7.5	15	750	1500	TUBE

■ (Typical)

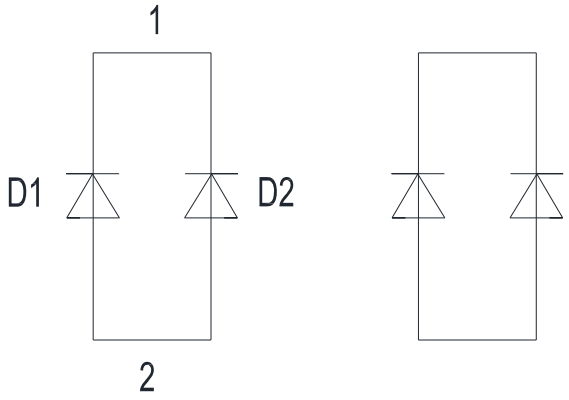








■



■

A	29.7	30.3
B	19.7	20.3
C	17.0	18.0
D	4.8	5.8
E	3.8	4.2
F	7.3	7.7
G	9.8	10.2
H	0.9	1.1
I	2.0	2.4
J	2.3	2.7
K	3.4	3.8
L	4.4	4.8
M	10.8	11.2
N	3.1	3.7
O	3.1	3.4
P	0.6	0.8
A1	28.75	29.15
B1	18.75	19.15
C1	0.3	0.7
D1	0.3	0.7

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website
e siu